

AMENDMENTS TO THE SPECIFICATION

Please replace Table 2 at page 20, line 1 with the following replacement Table 2, marked-up to show changes relative to the prior version:

Table 2

	Specific Gravity of Resin Composition	Fracture Rate X	Fractured Micro Hollow Body (E) (wt%)	(D+E)/C	Relative Dielectric Constant	Dielectric Dissipation Factor	Soldering Heat Resistance (°C)	Surface Property of Product	Flowability Evaluation
Example 1	1.11	0.048	1.0	0.05	2.73	0.026	330	o	o
Example 2	1.01	0.045	1.4	0.05	2.64	0.023	325	o	o
Example 3	1.20	0.085	1.3	0.42	2.91	0.030	330	o	o
Example 4	1.04	0.094	3.0	0.34	2.85	0.026	330	o	o
Example 5	1.04	0.088	2.8	0.34	2.86	0.027	320	o	o
Example 6	1.07	0.090	3.6	0.09	2.84	0.023	320	o	o
Comparative Example 1	1.06	0.0486 <u>0.456</u>	27.4	0.46	3.11	0.022	330	x	x
Comparative Example 2	1.38	—	—	—	3.02	0.035	300	x	o
Comparative Example 3	1.24	0.0460 <u>0.360</u>	10.8	0.36	3.12	0.031	330	o	o
Comparative Example 4	1.02	0.071	2.1	0.07	2.68	0.025	300 or less	o	o
Comparative Example 5	1.60	—	—	—	3.61	0.033	340	o	o
Comparative Example 6	1.62	—	—	—	3.65	0.034	330	o	o